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Speech subject: Recent Progress in Surface Activated Bonding for WBG Semiconductors and All-Metal 3D Interconnects

Speech leader: Tadatomo SUGA, Professor Emeritus of the University of Tokyo, Professor of Meisei University

Introduction of Speaker:

Prof. Tadatomo Suga joined the Max-Planck Institut für Metallforschung in 1979, obtained his Ph.D. degree in materials science from University of Stuttgart in 1983. Since 1984 he has been a faculty member of the University of Tokyo and a professor in the Department of Precision Engineering of the School of Engineering since 1993. He was also the director of the Research Group of Interconnect Ecodesign at the National Institute of Materials Science (NIMS), a Member of the Japan Council of Science, and the Chair of IEEE CPMT Society Japan Chapter, as well as the President of the Japan Institute for Electronic Packaging (JIEP).

His research focus on microsystems integration and packaging and developing interconnect technology, especially the room temperature bonding technique for 3D integration. He has endeavored to establish collaboration between industries and academia for packaging technology, direct the R&D project of the Institute of Micro System Integration (IMSI), and also advocate the importance of the environmental aspects of packaging technology as the key organizer of the International Eco-design Conference.

In March 2019, he retired from the University of Tokyo and joined Meisei University to continue his research.